ABSTRACT OF THE DISCLOSURE

BUMP BONDER

The object is to provide a bump bonder wherein the drop of the tact efficiency of bump formation can be reduced to a low level by discard-bonding of unsatisfactory balls (3) so that satisfactory bumps can be formed. It features arranging a discard bonding chip (19) on bonding stage (17), which holds in their prescribed positions the semiconductor chips (13a), (13b) that are to be subjected to bump formation, adjacent these prescribed positions, and performing discard bonding to discard bonding chip (19). Thanks to this construction, discard bonding can be effected without needing to move the capillary much from the bonding stage (17), which is the working position.

Figure 1.

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